

WHAT IS CLAIMED IS:

1. An electronic unit comprising:

a module in which a semiconductor device is attached on  
5 the bottom of a circuit board and which has lands provided on  
the bottom of the circuit board with the lands being  
connected to the semiconductor device; and

a printed circuit board on which the module is mounted,  
the printed circuit board having a hole in a position  
10 facing the semiconductor device and having electrical  
conductors to which the lands are soldered,

wherein the module is mounted on the printed circuit  
board by soldering the lands to the electrical conductors  
while the semiconductor device is disposed in the hole.

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2. An electronic unit according to Claim 1, wherein  
solder balls are applied on the lands, and the lands and the  
electric conductors are soldered together with the solder  
balls.

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3. An electronic unit according to Claim 2, wherein the  
wall of the hole has recesses that receive the corresponding  
solder balls and have electrical conductors applied to the  
walls of the recesses.